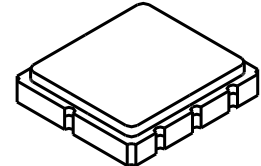


RF3626D

**315 MHz
SAW Filter**



**SM3838-8 Case
3.8 x 3.8**

- *Ideal Front-End Filter for European Wireless Receivers*
- *Low-Loss, Coupled-Resonator Quartz Design*
- *Simple External Impedance Matching*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*
- *AEC-Q200 Qualified*

Rating	Value	Units
Input Power Level	13	dBm
DC Voltage	0	VDC
Storage Temperature	-40 to +85	°C
Operable Temperature Range (Note 1)	-40 to +105	°C
Operable Temperature Range (Note 2)	-40 to +125	°C
Moisture Sensitivity Level	1	MSL
Solder Reflow Temperature, 5 Cycles Maximum	260°C for 10 seconds	

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency	f_c			315		MHz
Minimum Insertion Loss @ 315 MHz	IL_{min}			2.0	3.0	dB
3dB BW Passband (relative to 315 MHz) 3dB Low 3dB High			315.530	314.300 315.700	314.470	MHz
Attenuation (relative to 0 dB)						dB
10 to 140 MHz			65	71		
140 to 235 MHz			57	62		
235 to 300 MHz			41	43		
300 to 310 MHz			23	34		
310 to 313 MHz			9	14		
317 to 320 MHz			9	14		
320 to 325 MHz			11	13		
325 to 332 MHz			23	26		
332 to 352 MHz			36	41		
352 to 390 MHz			47	52		
390 to 1600 MHz			55	60		
1600 to 2500 MHz			50	55		
Package Size			SMD 3.8 X 3.8			mm
Lid Symbolization (Y=year WW=week S=shift)	A69, <u>YWWS</u>					

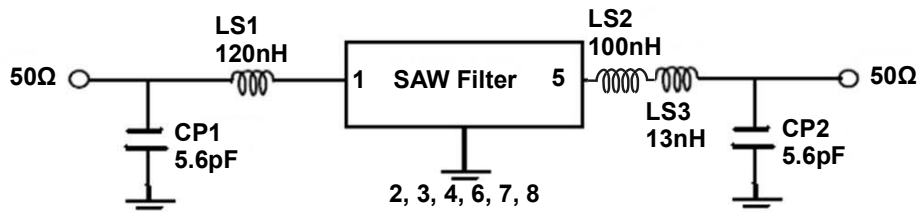


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

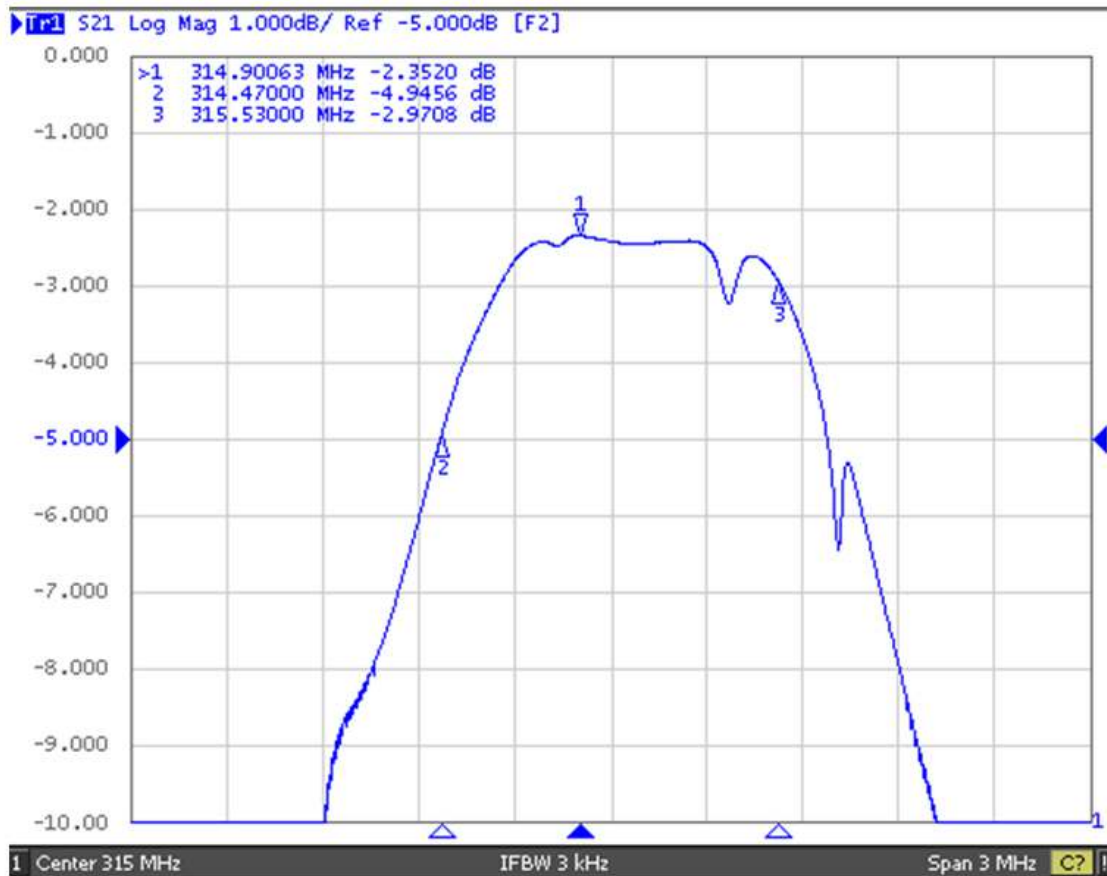
Measurement Circuit



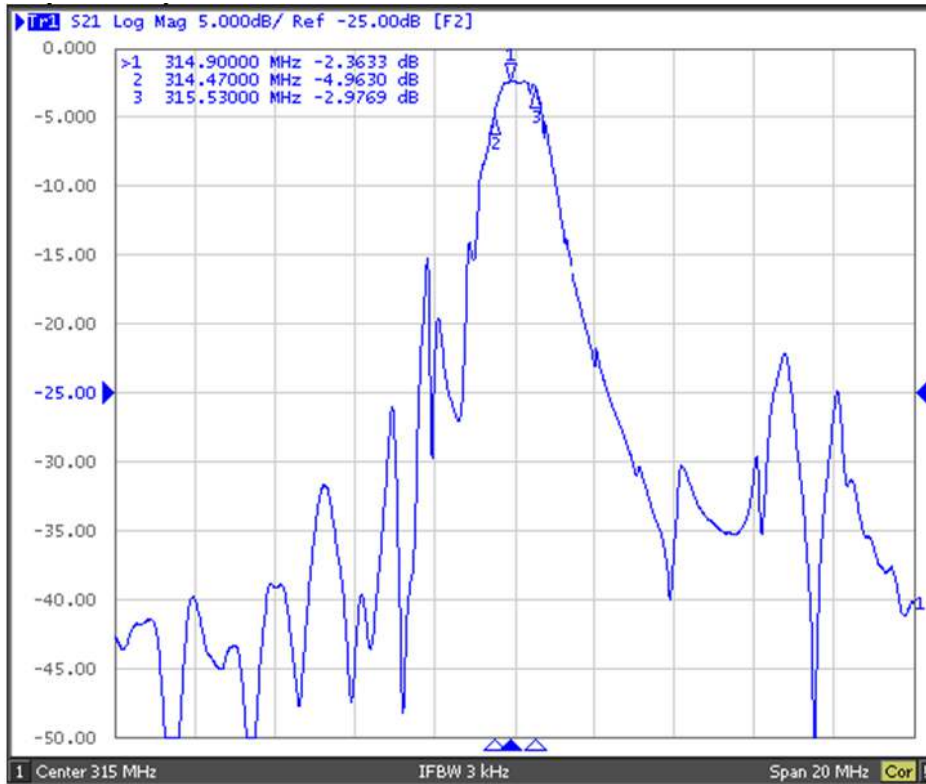
Pin	Connection
1	Input or Input Ground
2	Input Ground or Input
5	Output or Output Ground
6	Output Ground or Output
3, 4, 7, 8	Ground

Frequency Characteristics

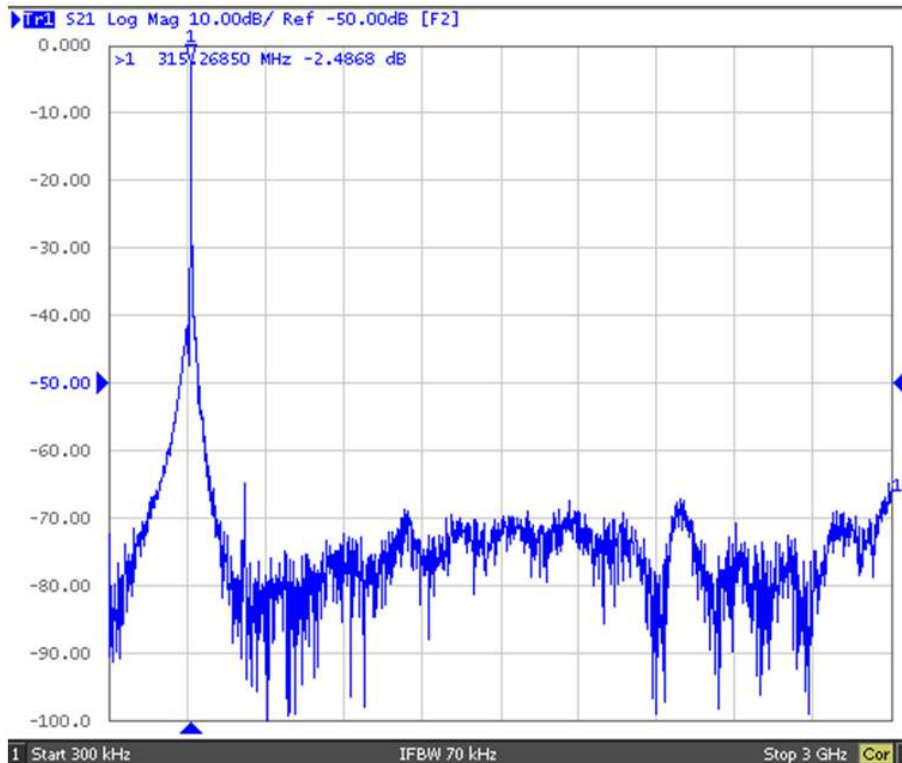
S21 Response: Span 5 MHz



S21 Response: Span 20 MHz



S21 Response: Span 1 MHz to 3 GHz

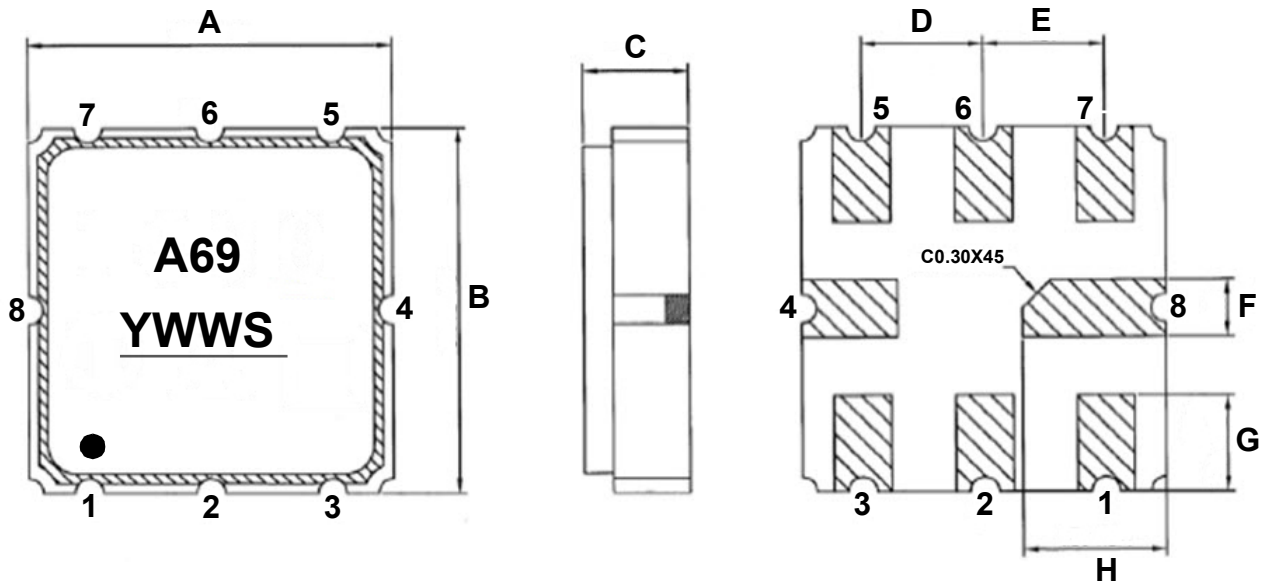


SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint

Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.65	3.8	3.95	0.143	0.149	0.155
B	3.65	3.8	3.95	0.143	0.149	0.155
C	-	-	1.7	-	-	0.066
D	-	1.27	-	-	0.050	-
E	-	1.27	-	-	0.050	-
F	-	0.60	-	-	0.023	-
G	-	1.00	-	-	0.039	-
H	-	1.50	-	-	0.059	-

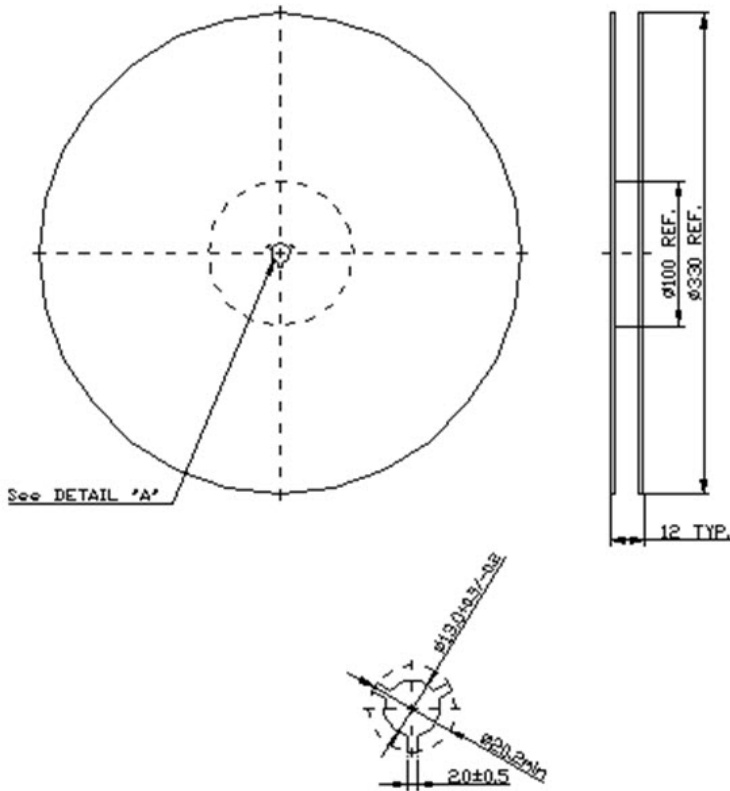


Case Materials

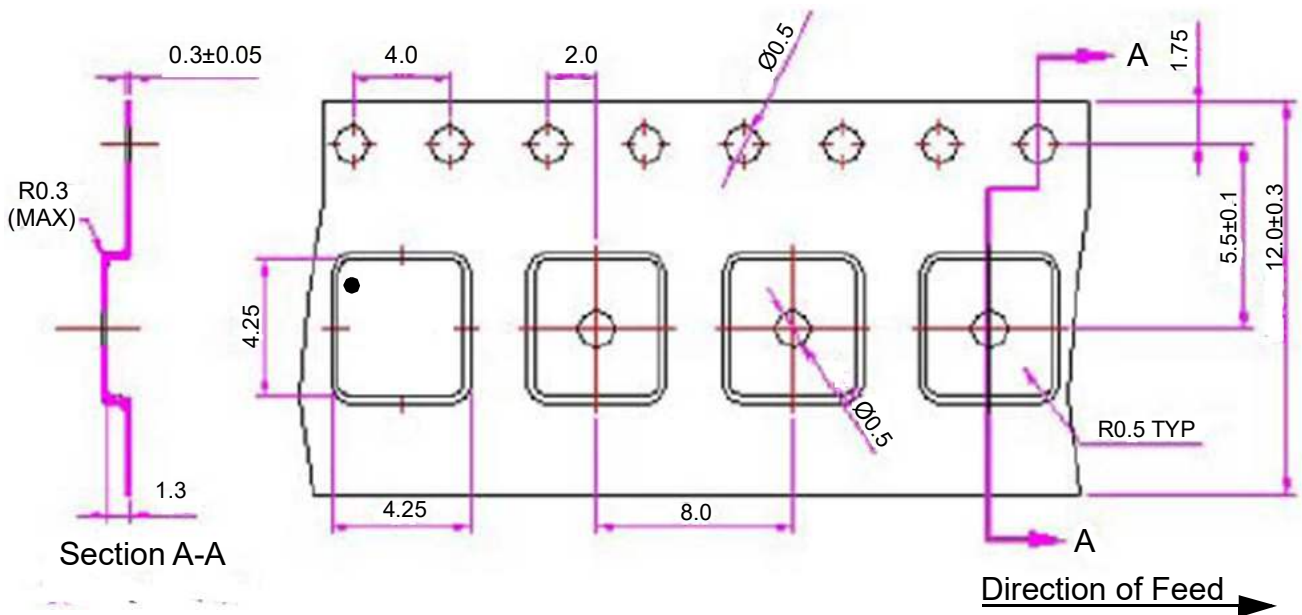
Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

Reel Dimensions

Tape and Reel Standard per ANSI/EIA-481



Tape Dimensions



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

